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#### 60V PNP MEDIUM POWER TRANSISTOR PowerDI<sup>®</sup>5

#### **Features**

- 43% smaller than SOT223; 60% smaller than TO252
- Maximum height just 1.1mm
- Rated up to 3.2W
- V<sub>CEO</sub> = 60V
- I<sub>C</sub> = -5.5A; I<sub>CM</sub> = 15A
- Low Saturation voltage
- Lead, Halogen, and Antimony Free/RoHS Compliant (Note 1)
- "Green" Device (Note 2)

### **Applications**

- Motor driver
- Regulator circuit

#### **Mechanical Data**

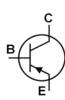
- Case: PowerDI<sup>®</sup>5
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper leadframe.
   Solderable per MIL-STD-202, Method 208 ®
- Weight: 0.093 grams (approximate)



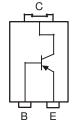
Top View



**Bottom View** 



**Device Schematic** 



Pin-out diagram

#### Ordering Information (Note 3)

Part Number	Case	Packaging
DXT2012P5-13	PowerDI <sup>®</sup> 5	5000/Tape & Reel

Notes:

- 1. No purposefully added lead. Halogen and Antimony Free.
- 2. Diodes Inc's "Green" Policy can be found on our website at http://www.diodes.com
- 3. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

### **Marking Information**



DXT2012 = Product Type Marking Code

Oli = Manufacturers' Code Marking

K = Factory Designator

YYWW = Date Code Marking

YY = Last Two Digits of Year (ex: 09 for 2009)

WW = Week code 01 to 53





### Maximum Ratings @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	-100	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-60	V
Emitter-Base Voltage	V <sub>EBO</sub>	-7	V
Continuous Collector Current	Ic	-5.5	Α
Peak Pulse Current	I <sub>CM</sub>	-15	А

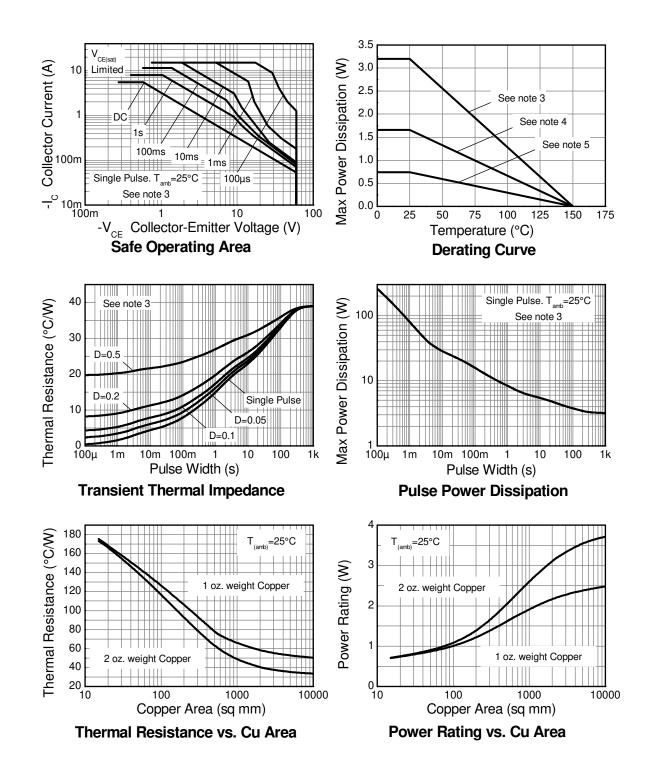
### **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation @ T <sub>A</sub> = 25°C (Note 4)	$P_{D}$	3.2	W
Thermal Resistance, Junction to Ambient Air (Note 4) @T <sub>A</sub> = 25°C	$R_{ hetaJA}$	39	°C/W
Power Dissipation @ T <sub>A</sub> = 25°C (Note 5)	$P_{D}$	1.7	W
Thermal Resistance, Junction to Ambient Air (Note 5) @T <sub>A</sub> = 25°C	$R_{ hetaJA}$	75	°C/W
Power Dissipation @ T <sub>A</sub> = 25°C (Note 6)	$P_{D}$	0.74	W
Thermal Resistance, Junction to Ambient Air (Note 6) @T <sub>A</sub> = 25°C	$R_{ hetaJA}$	169	°C/W
Thermal Resistance, Junction to Collector Terminal	$R_{ heta JT}$	5.6	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

Notes:

- Device mounted on FR-4 PCB, single sided 2 oz. copper, collector pad dimensions 50mm x 50mm.
   Device mounted on FR-4 PCB, single sided 1 oz. copper, collector pad dimensions 25mm x 25mm.
   Device mounted on FR-4 PCB, 2 single sided 1oz. copper, minimum recommended pad layout.









### **Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

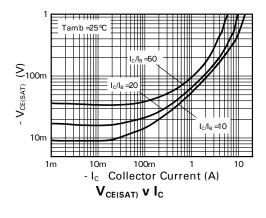
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	$V_{(BR)CBO}$	-100	-120	-	V	$I_C = -100 \mu A$
Collector-Emitter Breakdown Voltage (Note 7)	V <sub>(BR)CEO</sub>	-60	-80	-	V	I <sub>C</sub> = -10mA
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	-7	-8.1	-	V	$I_E = -100 \mu A$
Collector Cutoff Current	I <sub>CBO</sub>	-	<1	-20	nA	V <sub>CB</sub> = -80V
Concetor Cuton Current	ICBO		_	-0.5	μΑ	V <sub>CB</sub> = -80V, T <sub>amb</sub> = 100 °C
Collector Cutoff Current	ICER		<1	-20	nA	$V_{CB} = -80V$
Collector Caton Carrent	R≤1kΩ		-	-0.5	μΑ	V <sub>CB</sub> = -80V, T <sub>amb</sub> = 100 °C
Emitter Cutoff Current	I <sub>EBO</sub>	_	<1	-10	nA	V <sub>EB</sub> = -6V
	V	_	-15	-25	mV	$I_C = -0.1A$ , $I_B = -10mA$
Collector-Emitter Saturation Voltage (Note 7)		-	-55	-70		$I_C = -1A$ , $I_B = -100mA$
Collector-Entitler Saturation Voltage (Note 1)	V <sub>CE(sat)</sub>	_	-90	-120		$I_C = -2A$ , $I_B = -200mA$
		-	-195	-250		$I_C = -5A$ , $I_B = -500mA$
Base-Emitter Saturation Voltage (Note 7)	$V_{BE(sat)}$	-	-1030	-1150	mV	$I_C = -5A$ , $I_B = -500mA$
Base-Emitter Turn-On Voltage (Note 7)	V <sub>BE(on)</sub>	-	-920	-1020	mV	$V_{CE} = -1V, I_{C} = -5A$
		100	250	=		$V_{CE} = -1V, I_{C} = -10mA$
DC Current Gain (Note 7)	h	100	200	300		$V_{CE} = -1V, I_{C} = -2A$
Do Guiterii Gairi (Note 1)	h <sub>FE</sub>	45	90	-	_	$V_{CE} = -1V, I_{C} = -5A$
		10	25	-		$V_{CE} = -1V, I_{C} = -10A$
Transition Frequency	f⊤	_	120	-	MHz	$V_{CE} = -10V$ , $I_{C} = -100mA$ ,
' '						f = 50MHz
Output Capacitance	$C_{obo}$	_	48	_	pF	V <sub>CB</sub> = -10V, f = 1MHz
Switching Times	t <sub>on</sub>	_	39	-	ns	$V_{CC} = 10V, I_{C} = 1A,$
Cintorning Timos	t <sub>off</sub>	-	370	-	10	$I_{B1} = I_{B2} = -100 \text{mA}$

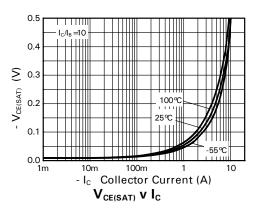
Notes: 7. Pulse Test: Pulse width  $\leq 300 \mu s$ . Duty cycle  $\leq 2.0\%$ .

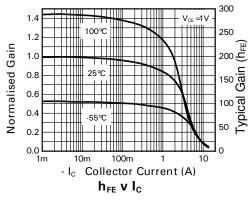


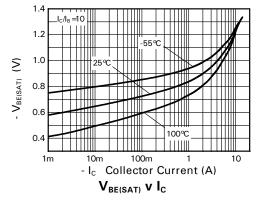


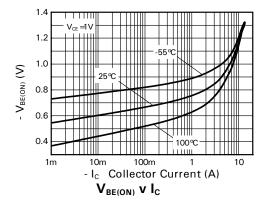
# **Typical Characteristic**





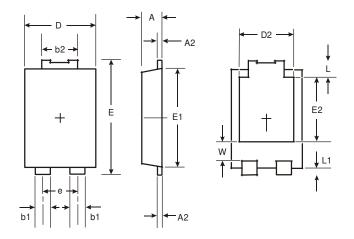






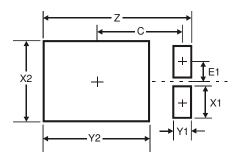


## **Package Outline Dimensions**



PowerDI <sup>®</sup> 5				
Dim	Min	Max		
Α	1.05	1.15		
A2	0.33	0.43		
b1	0.80	0.99		
b2	1.70	1.88		
D	3.90	4.05		
D2	3.054 Typ			
E	6.40	6.60		
е	1.84 Typ			
E1	5.30	5.45		
E2	3.549 Typ			
L	0.75	0.95		
L1	0.50	0.65		
W	1.10	1.41		
All Dimensions in mm				

# **Suggested Pad Layout**



Dimensions	Value (in mm)
Z	6.6
X1	1.4
X2	3.6
Y1	0.8
Y2	4.7
С	3.87
E1	0.0





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